

1.1 Scope.

This specification covers the detail requirements for a monolithic CMOS multiplying digital-to-analog converter (LOGDAC®) that can attenuate an analog signal over the range 0 to -88.5dB in 0.375dB steps.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number ¹
-1	AD7111T(X)/883B
-2	AD7111U(X)/883B

NOTE

¹See paragraph 1.2.3 for package identifier.

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
E	E-20A	20-Terminal LCC
Q	Q-16	16-Pin Cerdip

1.3 Absolute Maximum Ratings. ($T_A = 25^\circ\text{C}$ unless otherwise noted)

V_{DD} to GND		+7V
V_{IN} to AGND		+35V
Digital Input Voltage to DGND		-0.3V, V_{DD}
Output Voltage (Pin 1) to AGND		-0.3V, V_{DD}
V_{RFB} to AGND		$\pm 35V$
AGND to DGND		0 to V_{DD}
DGND to AGND		0 to V_{DD}
Power Dissipation		
Up to $+75^\circ\text{C}$		450mW
Derate above $+75^\circ\text{C}$		6mW/ $^\circ\text{C}$
Operating Temperature Range		-55°C to $+125^\circ\text{C}$
Storage Temperature Range		-65°C to $+150^\circ\text{C}$
Lead Temperature (Soldering 10sec)		$+300^\circ\text{C}$

NOTE

Pin numbers refer to DIP package ONLY.

1.5 Thermal Characteristics.

Thermal Resistance $\theta_{JC} = 35^\circ\text{C}/\text{W}$ for Q-16 and E-20A
 $\theta_{JA} = 120^\circ\text{C}/\text{W}$ for Q-16 and E-20A

LOGDAC is a registered trademark of Analog Devices, Inc.

AD7111—SPECIFICATIONS

Table 1.

Test	Symbol	Device	Design Limit T_{min} to T_{max}	Sub Group 1	Sub Group 2, 3	Sub Group 4	Test Condition ¹	Units
Gain Error	A_E	-1 -2	0.20 0.15	0.15 0.15	0.2 0.15	0.10		± dB max
0.375dB Steps: Accuracy = ± 0.17dB ²	RA	-1 -2	0-30 0-36	0-30 0-30	0-30 0-36	0-36		dB min
0.75dB Steps: Accuracy = ± 0.35dB ²	RA	-1 -2	0-36 0-42	0-42 0-42	0-36 0-42	0-48		dB min
1.5dB Steps: Accuracy = ± 0.7dB ²	RA	-1 -2	0-42 0-48	0-48 0-48	0-42 0-48	0-54		dB min
3.0dB Steps: Accuracy = ± 1.4dB ²	RA	-1 -2	0-48 0-54	0-60 0-60	0-48 0-54	0-66		dB min
6.0dB Steps: Accuracy = ± 2.7dB ²	RA	-1 -2	0-60 0-60	0-60 0-60	0-60 0-60	0-72		dB min
Nominal 0.375dB Step ³	MR	-1 -2	0-48 0-54	0-48 0-48	0-48 0-54	0-54		dB min
Nominal 0.75dB Step ³	MR	-1 -2	0-60 0-66	0-72 0-72	0-60 0-66			dB min
Nominal 1.5dB Step ³	MR	-1 -2	0-72 0-78	0-85.5 0-85.5	0-72 0-78	0-88.5		dB min
Nominal 3.0dB Step ³	MR	-1, 2	0-88.5	0-88.5	0-88.5			dB min
Nominal 6.0dB Step ³	MR	-1, 2	0-88.5	0-88.5	0-88.5			dB min
DC Supply Rejection	PSR	-1, 2	0.005				$\Delta V_{DD} = \pm 10\%$ Input Data Latch Loaded with 0000 0000	± dB per % max
Propagation Delay	t_{PD}	-1, 2	4.5				$R_{OUT1} = 100\Omega$, $C_{OUT1} = 13pF$; Time required for the output current to reach 90% of its final value for a Full Scale Change. Measured from $\overline{WR}$ going high, $\overline{CS} = 0V$.	µs max
Feedthrough ⁴	FT	-1 -2	68 72				Full scale Change. Measured from $\overline{WR}$ going high, $\overline{CS} = 0V$. $V_{IN} = 6V$ rms, 1kHz sinewave. Input Data loaded with 1111 1111.	- dB max
Output Capacitance	C_{OUT}	-1, 2	185					pF max
V_{IN} Input Resistance	R_{IN}	-1 -2 -1 -2	7 9 18 15	7 9 18 15	7 9 18 15			kΩ min kΩ max
R_{FB} Input Resistance	R_{FB}	-1 -2 -1 -2	7.3 9.3 18.8 15.7	7.3 9.3 18.8 15.7	7.3 9.3 18.8 15.7			kΩ min kΩ max
Input High Voltage	V_{IH}	-1, 2	2.4	2.4	2.4			V min
Input Low Voltage	V_{IL}	-1, 2	0.8	0.8	0.8			V max
Input Leakage Current	I_{IN}	-1, 2	10	1	10		Digital Inputs = V_{DD} or 0V	± µA max
Input Capacitance	C_{IN}	-1, 2	7					pF max
Supply Current	I_{DD}	-1, 2	4 1	1 0.5	4 1		Digital Inputs = V_{IH} or V_{IL} Digital Inputs = 0V or V_{DD}	mA max mA max
Chip-Select-to-Write Setup Time ⁵	t_{CS}	-1, 2	0					ns min
Chip-Select-to-Write Hold Time ⁵	t_{CH}	-1, 2	0					ns min
Write Pulse Width ⁵	t_{WR}	-1, 2	500					ns min
Data Valid to Write Setup Time ⁵	t_{DS}	-1, 2	250					ns min
Data Valid to Hold Time ⁵	t_{DH}	-1, 2	10					ns min
Refresh Time ⁵	t_{RFSH}	-1, 2	4.5					ns min

NOTES

¹ $V_{DD} = +5V$; $V_{PIN1} = V_{PIN2} = 0V$; $V_{IN} = -10V$.

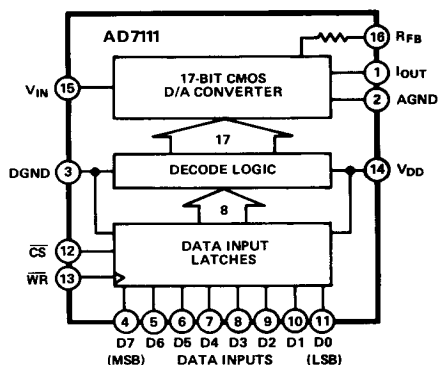
²Accuracy is measured using the internal R_{FB} and includes effects of leakage current and gain TC.

³Monotonic range for specified step.

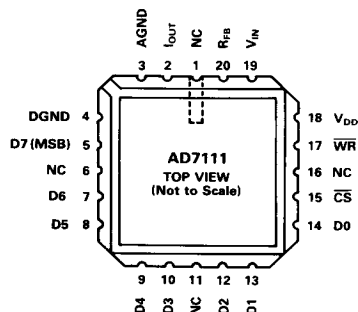
⁴Feedthrough can be further reduced by connecting the metal lid to ground.

⁵Timing per Figure 1.

3.2.1 Functional Block Diagram and Terminal Assignments.



E Package (LCC)

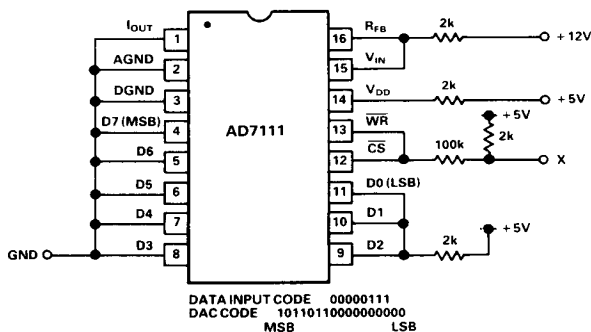


3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (80).

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).



NOTE
ON POWER UP APPLY 0V TO POINT X TO
LOAD THE INPUT DATA INTO THE DAC.

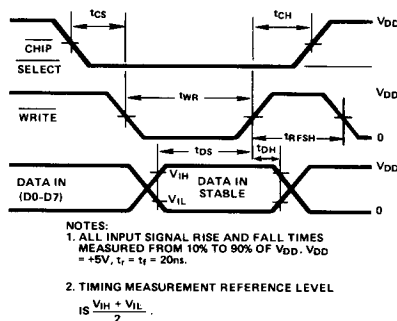


Figure 1. Write Cycle Timing Diagram

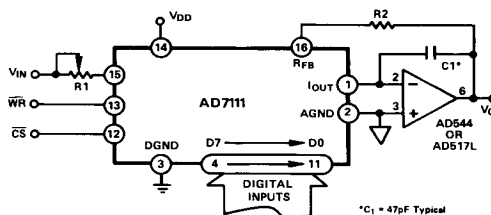


Figure 2. Typical Circuit Configuration

Table 2. Ideal Attenuation in dB vs. Input Code

[illegible]